TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)

## 2SK2986

# DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain-source ON resistance :  $RDS(ON) = 4.5 \text{ m}\Omega \text{ (typ.)}$ 

• High forward transfer admittance  $|Y_{fs}| = 80 \text{ S (typ.)}$ 

• Low leakage current :  $IDSS = 100 \mu A (max) (VDS = 60 V)$ 

• Enhancement-mode :  $V_{th} = 1.3 \sim 2.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

#### Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			$V_{DSS}$	60	V
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)			$V_{DGR}$	60	V
Gate-source voltage			V <sub>GSS</sub>	±20	V
Drain current	DC (Note	1)	ΙD	55	
	Pulse (t≤10 s) (Note	1)	I	70	Α
	Pulse (t≤1 ms) (Note	1)	I <sub>DP</sub>	280	
Drain power dissipation (Tc = 25°C)			$P_{D}$	100	W
Single pulse avalanche energy (Note 2)		2)	E <sub>AS</sub>	525	mJ
Avalanche current			$I_{AR}$	55	Α
Repetitive avalanche energy (Note 3)		3)	E <sub>AR</sub>	10	mJ
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature range			T <sub>stg</sub>	-55~150	°C

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.25	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

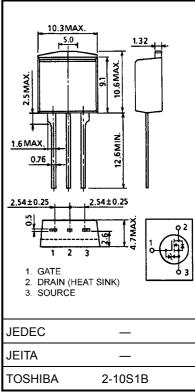
Note 2:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 236  $\mu$ H,  $I_{AR}$  = 55 A,  $R_G$  = 25  $\Omega$ 

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

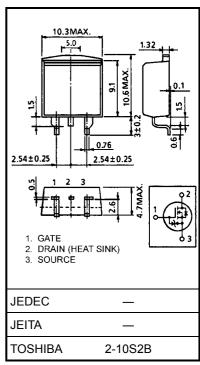
This transistor is an electrostatic sensitive device.

Please handle with caution.





Weight: 1.5 g (typ.)



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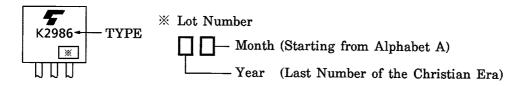
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source breakdown voltage		V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	V
		V <sub>(BR)DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	40	_	1	
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.3	_	2.5	V
Drain-source O	N resistance	<b>D</b>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 35 A	_	4.5	5.8	mΩ
Drain-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 35 A	_	5.8	10	11177
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 35 A		80	_	S
Input capacitano	e	C <sub>iss</sub>			9300	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	910	_	
Output capacitance		Coss			1435	_	
Switching time –	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OV}$ $V_{DD}$ $V_{OUT}$ $V_{OD}$ $V_{OUT}$	_	18	_	
	Turn-on time	t <sub>on</sub>		_	50	_	- ns
	Fall time	t <sub>f</sub>		_	110	ı	
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_{\rm W} = 10 \mu \rm s$	_	480	l	
Total gate charge (gate-source plus gate-drain)		Qg		_	210	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 55 \text{ A}$		145	_	nC
Gate-drain ("miller") Charge		Q <sub>gd</sub>		_	65	_	

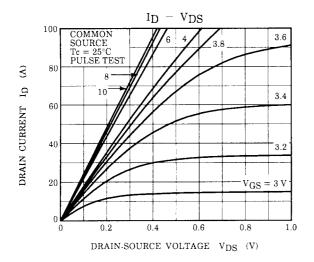
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

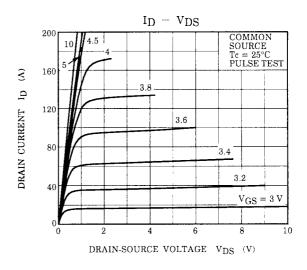
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_		_	55	Α
Pulse drain reverse current (Note 1)	$I_{DRP}$	t ≤ 10 s	_	_	70	А
		t ≤ 1 ms	_	_	280	
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 55 A, V <sub>GS</sub> = 0 V		_	-1.5	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 55 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 50 A / μs	_	60		ns
Reverse recovery charge	Q <sub>rr</sub>	1DR - 33 A, VGS - 0 V, αιDR / αι - 30 A / μs	-	50	_	nC

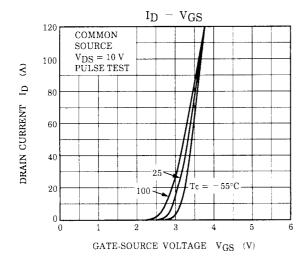
## Marking

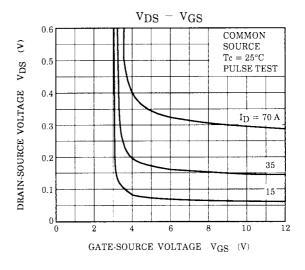


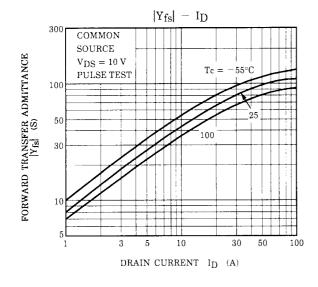
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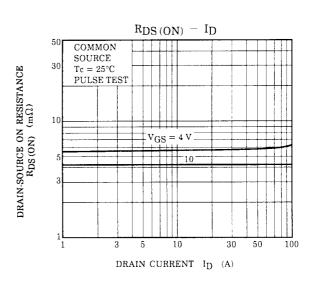






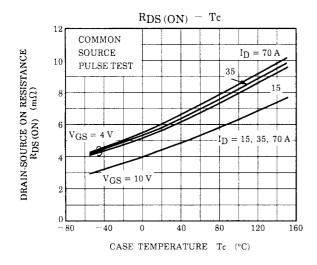


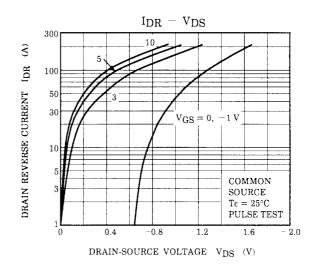


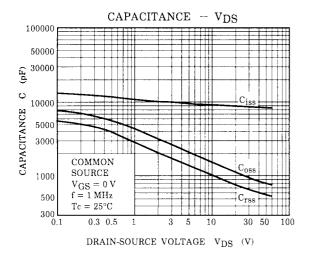


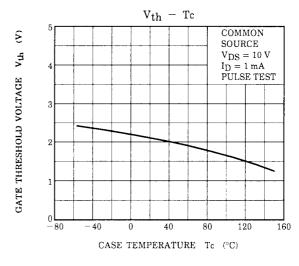
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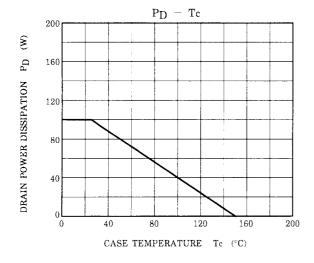
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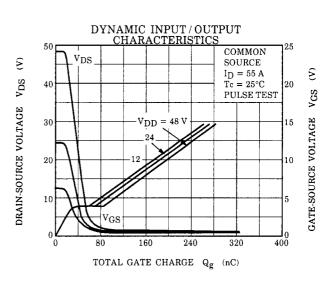




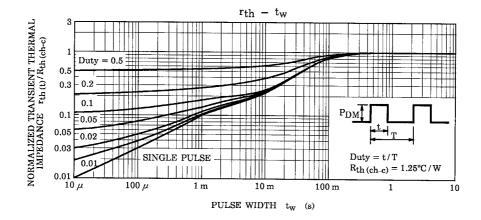


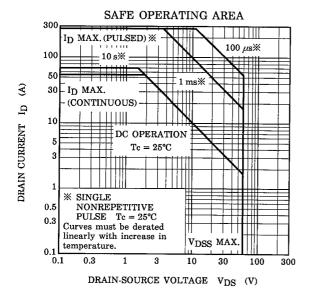


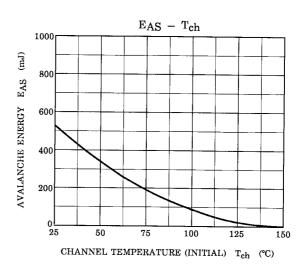


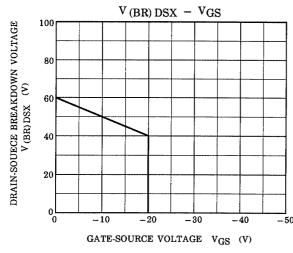


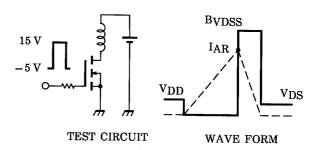
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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 25~V,~L = 236~\mu H \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - V_{DD}} \right) \end{aligned}$$

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